Image Sensor Package with Die Receiving Opening and Method of the Same

ABSTRACT OF THE INVENTION

The present invention provides a structure of package comprising a substrate with a die through hole and a contact through holes structure formed there through, wherein a terminal pad is formed under the contact through hole structure and a contact pad is formed on a upper surface of the substrate. A die having a micro lens area is disposed within the die through hole by adhesion. A wire bonding is formed on the die and the substrate, wherein the wire bonding is coupled to the die and the contact pad. A protective layer is formed to cover the wire bonding. A transparent cover is disposed on the die within the die through hole by adhesion to expose the micro lens area. Conductive bumps are coupled to the terminal pads.

(Fig. 1)